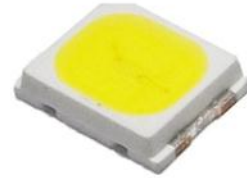


ST28PF Studio Lighting LEDs datasheet

The studio lighting LED products exhibit qualities closest to the reference source with high CRI, high fidelity and color gamut indexes, which dramatically enhance the appearance of products by allowing colors to appear clear, vivid. Furthermore, the high TLCI value meets a perfect match with modern television systems .



The Studio lighting with high CRI ($R_a=98\pm 2$, $R_f\geq 93$, $R_g=100\pm 2$) have been achieved without sacrificing the lumen efficiency, reliability, and cost.

FEATURES

- High CRI;
- $R_1-R_{15} > 90$
- High R_f ; R_g (TM-30-15)
- High TLCI Index
- ANSI-compatible chromaticity bins
- High luminous Intensity and high efficiency
- Compatible with reflow soldering process
- Low thermal resistance
- Long operation life
- Wide viewing angle at 120°
- Silicone encapsulation
- Environmental friendly, RoHS compliance

APPLICATIONS

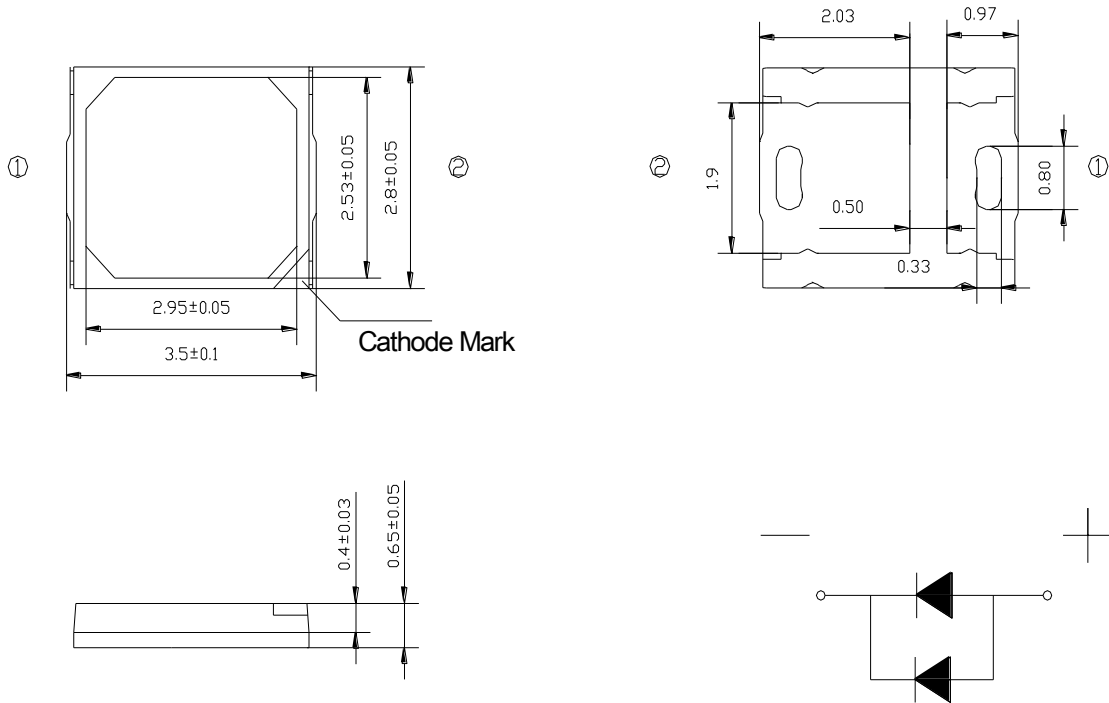
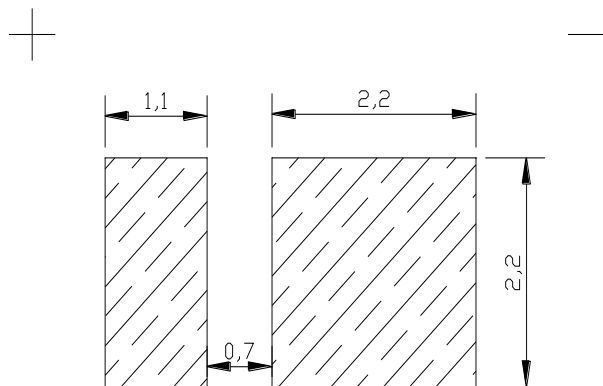
- Studio lighting
- Cinematography
- Framing projectors
- Film production lighting

Naming Conventions

SOW2835 - 32/56 - I - PF
 (1) (2) (3) (4)

- (1) SMD Series
- (2) CCT Range:3200K/5600K
- (3) Studio lighting series
- (4) Product Series Code

Note: The information in this document is subject to change without notice.

PACKAGE DIMENSIONS

Recommended Solder Pad Design

Notes:

1. All dimensions in millimeters.
2. Thickness tolerance of copper plate is ± 0.02 mm.
3. Thickness tolerance of product is ± 0.05 mm.
4. Tolerance is ± 0.1 mm unless otherwise noted.

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Absolute Maximum Rating	Unit
Forward current	I_F	180	mA
Peak Forward Current ^[1]	I_{FP}	400	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_d	576	mW
Operating Temperature	T_{opr}	-40~+85	°C
Storage Temperature	T_{stg}	-40~+100	°C
Soldering Temperature	T_{sld}	Reflow Soldering: 260°C for 10 seconds	
LED Junction Temperature	T_j	115	°C

Note:

 I_{FP} Conditions: Pulse Width $\leq 10\text{msec.}$ and Duty $\leq 1/10$.

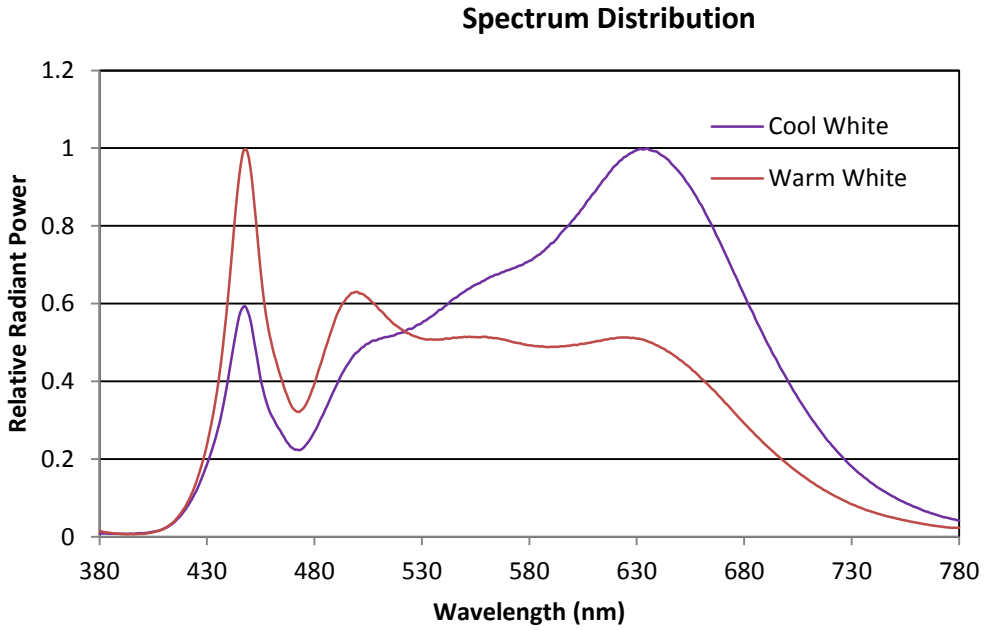
CHARACTERISTICS (T_j=25°C)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Forward Voltage ^[1]	V_F		2.8	3.0	3.2	V
Viewing Angle	$2\theta_{1/2}$		--	120	--	deg.
Luminous Flux	Φ_v		38	--	54	lm
Color Rendering Index	CRI	$I_F=150\text{mA}$	95	98	--	--
Color Fidelity Index	R _f		--	94	--	--
Color Gamut Index	R _g		98	100	102	--
Thermal Resistance (Junction to Solder Point)	R_{th-js}		--	30	--	°C/W
Reverse Current	IR	$V_r=5V$	--	--	10	uA

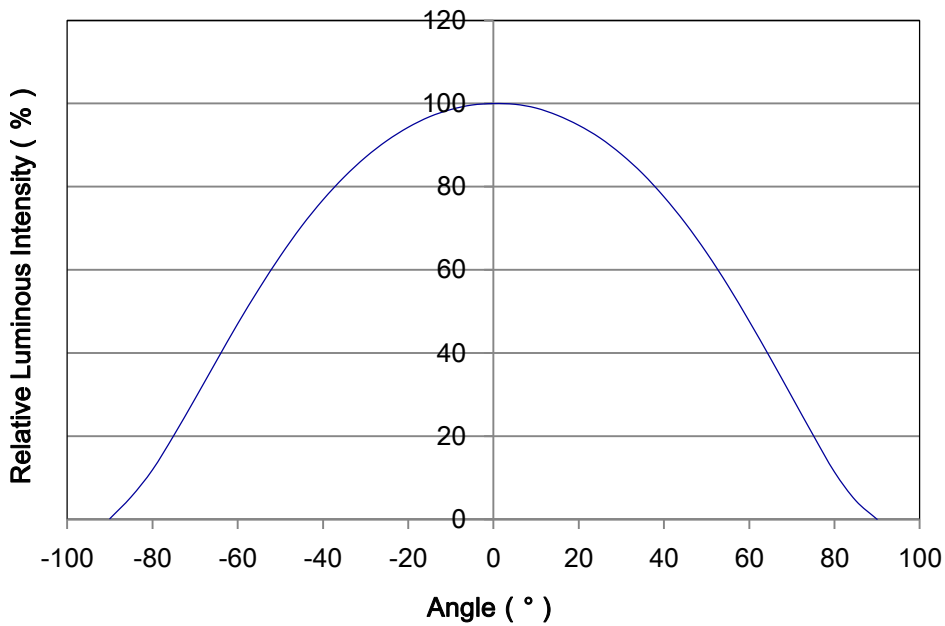
Notes:

- Luminous flux is measured with an accuracy of $\pm 10\%$.
- Chromaticity coordinate bins are measured with an accuracy of ± 0.01 .
- CRI is measured with an accuracy of ± 2 .
- All measurements were made under the standardized environment of Shineon

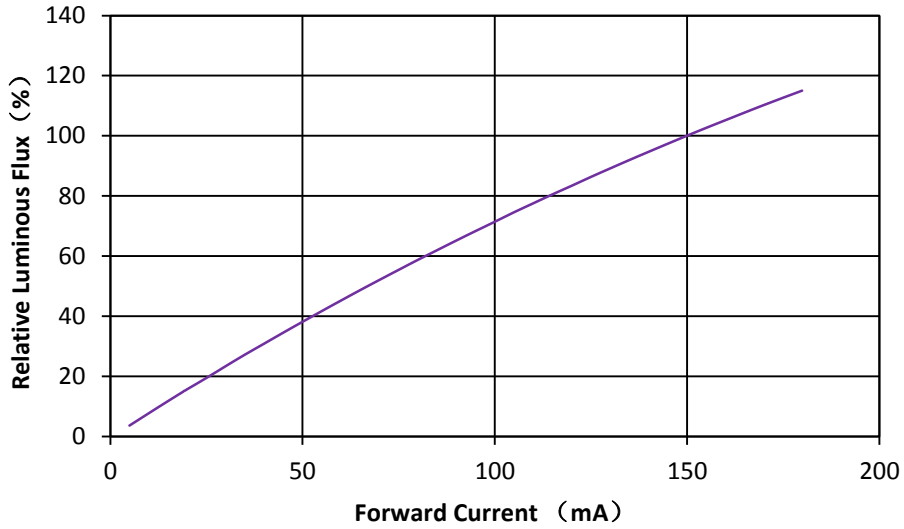
RELATIVE SPECTRAL POWER DISTRIBUTION ($T_j=25^{\circ}\text{C}$)



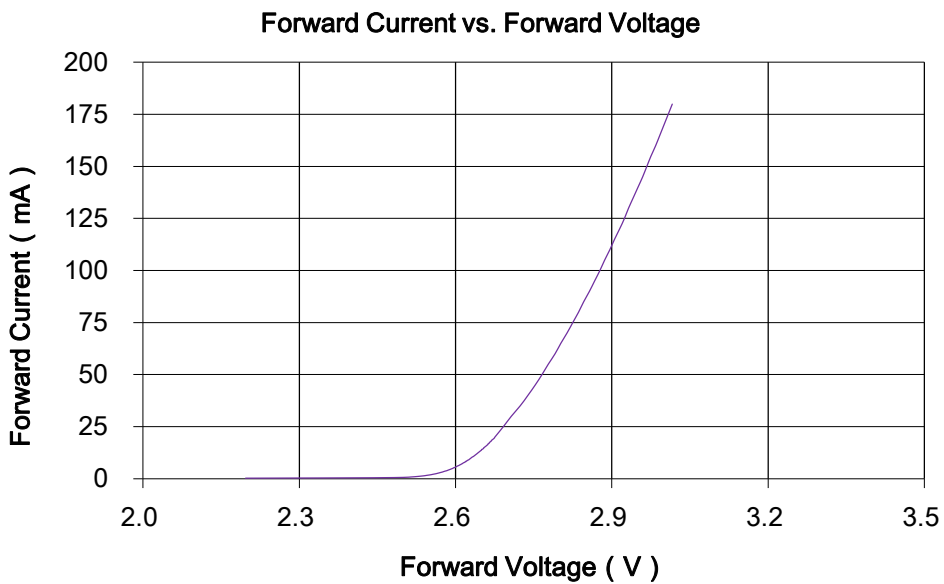
TYPICAL SPATIAL DISTRIBUTION



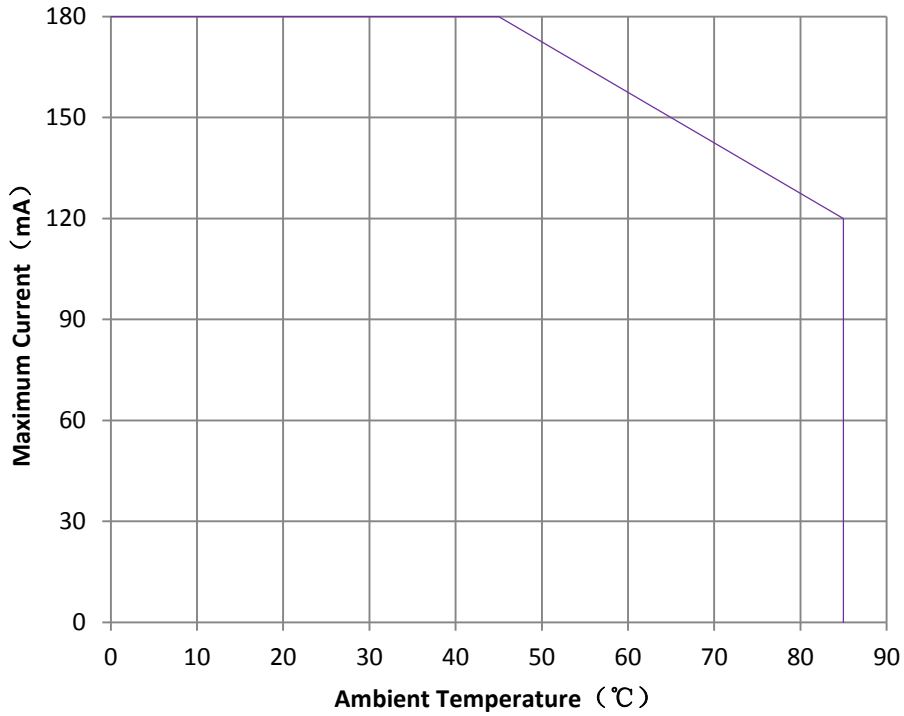
RELATIVE LUMINOUS FLUX VS. CURRENT ($T_j=25^{\circ}\text{C}$)



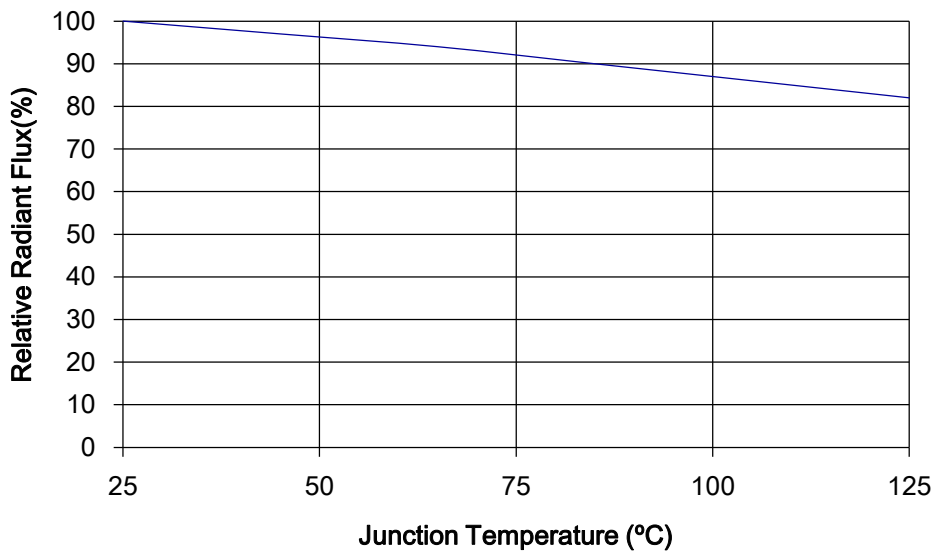
ELECTRICAL CHARACTERISTICS ($T_j=25^{\circ}\text{C}$)



MAXIMUM CURRENT VS. AMBIENT TEMPERATURE



RELATIVE RADIANT FLUX VS. JUNCTION TEMPERATURE



SORTING RANKS

(1) Luminous Flux (Tj=25°C)

Part Number	Condition	Rank			Unit
SOW2835-32-T-PF	150mA	OC	OD	OE	lm
		38-42	42-46	46-50	
SOW2835-56-T-PF		OD	OE	OF	
		42-46	46-50	50-54	

(2) Forward Voltage (Tj=25°C)

Rank	Condition	Min.	Max.	Unit
A8	150mA	2.8	2.9	V
A9		2.9	3.0	
B0		3.0	3.1	
B1		3.1	3.2	

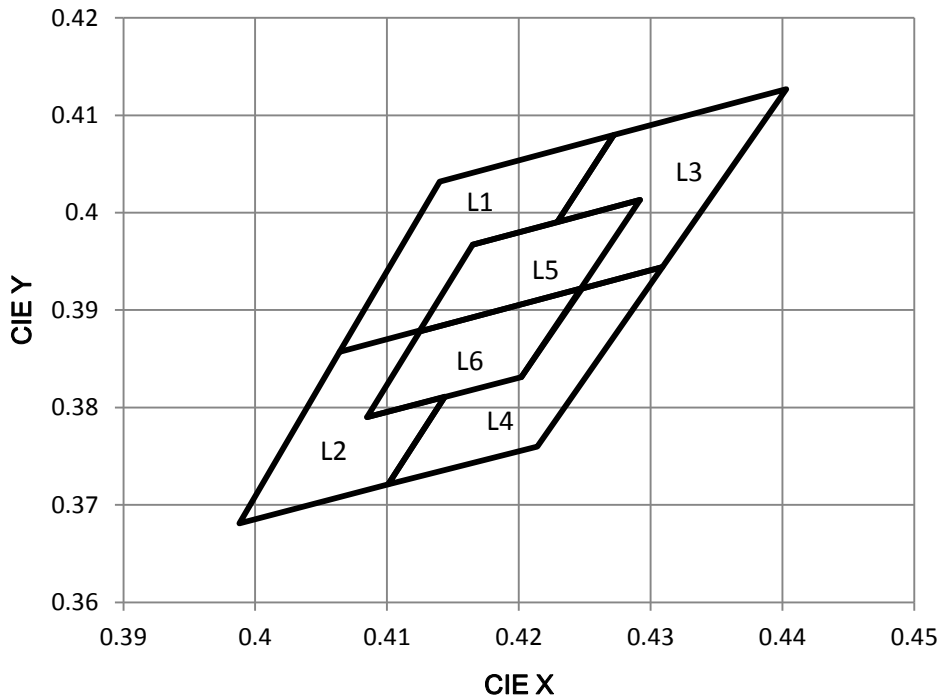
Notes:

- 5% tolerance for luminous intensity may be caused by measurement inaccuracy.
- Measurement Uncertainty of the Forward Voltage : $\pm 0.1V$

(3) Chromaticity Bins (Ta=85°C)

3200K (IF =150 mA)											
Rank		X	Y	Rank		X	Y	Rank		X	Y
L1	1	0.4064	0.3857	L3	1	0.4292	0.4013	L5	1	0.4165	0.3967
	2	0.414	0.4032		2	0.4229	0.399		2	0.4292	0.4013
	3	0.4272	0.4080		3	0.4272	0.408		3	0.4247	0.3922
	4	0.4229	0.3990		4	0.4403	0.4127		4	0.4125	0.3878
	5	0.4165	0.3967		5	0.4309	0.3944		5	--	--
	6	0.4125	0.3879		6	0.4248	0.3922		6	--	--
Rank		X	Y	Rank		X	Y	Rank		X	Y
L2	1	0.4125	0.3879	L4	1	0.4144	0.3811	L6	1	0.4125	0.3878
	2	0.4064	0.3857		2	0.4101	0.3721		2	0.4247	0.3922
	3	0.3988	0.3681		3	0.4214	0.376		3	0.4202	0.3831
	4	0.4101	0.3721		4	0.4309	0.3944		4	0.4085	0.379
	5	0.4144	0.3811		5	0.4248	0.3922		5	--	--
	6	0.4085	0.379		6	0.4202	0.3831		6	--	--

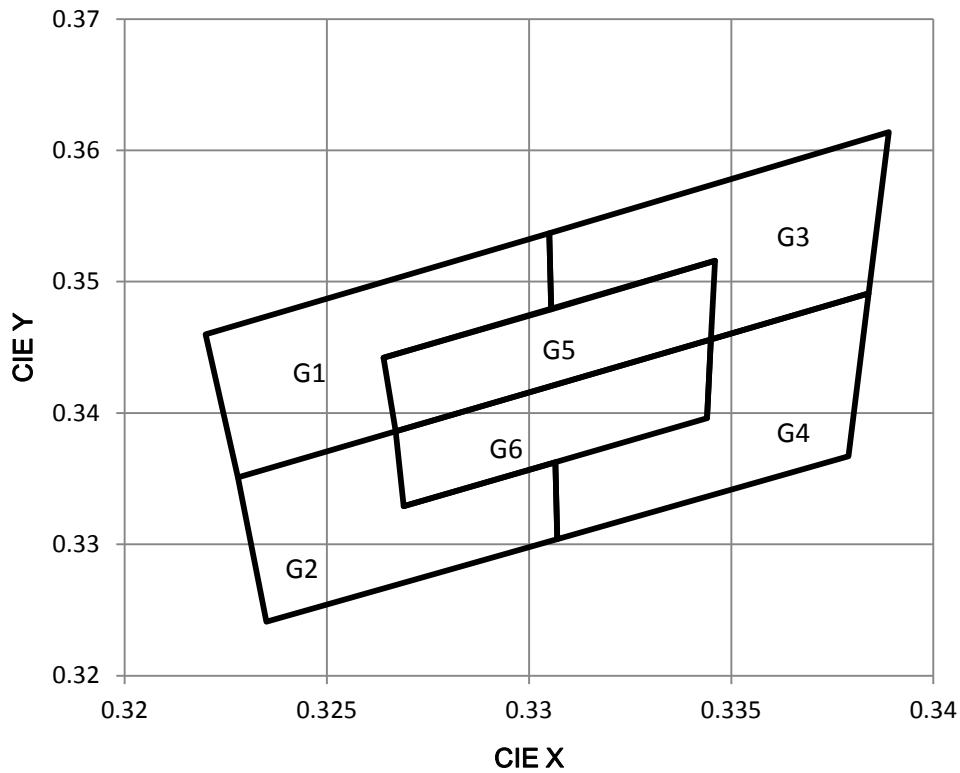
CCT 3200K BIN Structure



(3) Chromaticity Bins (Ta=85°C)

5600K (IF =150 mA)											
Rank		X	Y	Rank		X	Y	Rank		X	Y
G1	1	0.3228	0.3351	G3	1	0.3346	0.3516	G5	1	0.3264	0.3442
	2	0.322	0.346		2	0.3306	0.3479		2	0.3346	0.3516
	3	0.3305	0.3537		3	0.3305	0.3537		3	0.3345	0.3456
	4	0.3306	0.3479		4	0.3389	0.3614		4	0.3267	0.3386
	5	0.3264	0.3442		5	0.3384	0.3491		5	--	--
	6	0.3267	0.3386		6	0.3345	0.3456		6	--	--
Rank		X	Y	Rank		X	Y	Rank		X	Y
G2	1	0.3267	0.3386	G4	1	0.3344	0.3396	G6	1	0.3267	0.3386
	2	0.3228	0.3351		2	0.3345	0.3456		2	0.3345	0.3456
	3	0.3235	0.3241		3	0.3384	0.3491		3	0.3344	0.3396
	4	0.3307	0.3304		4	0.3379	0.3367		4	0.3269	0.3329
	5	0.3307	0.3363		5	0.3307	0.3304		5	--	--
	6	0.3269	0.3329		6	0.3307	0.3363		6	--	--

CCT 5600K BIN Structure



REFLOW SOLDERING CHARACTERISTICS

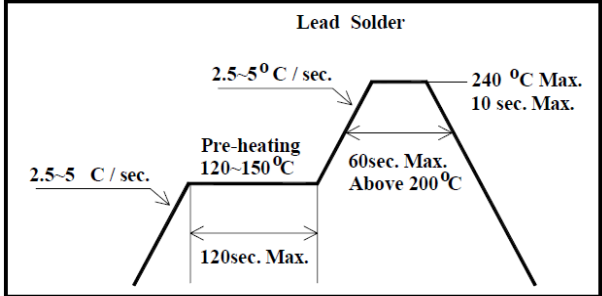
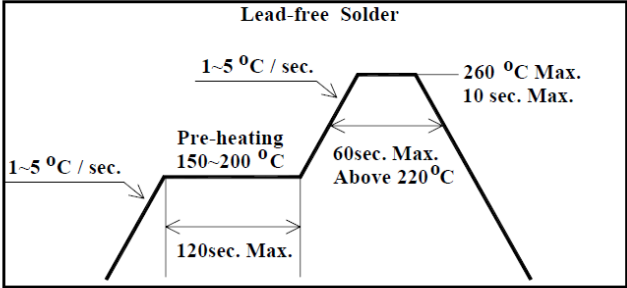
For Reflow Process:

Preheating : 140°C~160°C±5°C, within 2 minutes.

Operation heating : 260°C(Max.) within 10 seconds.(Max)

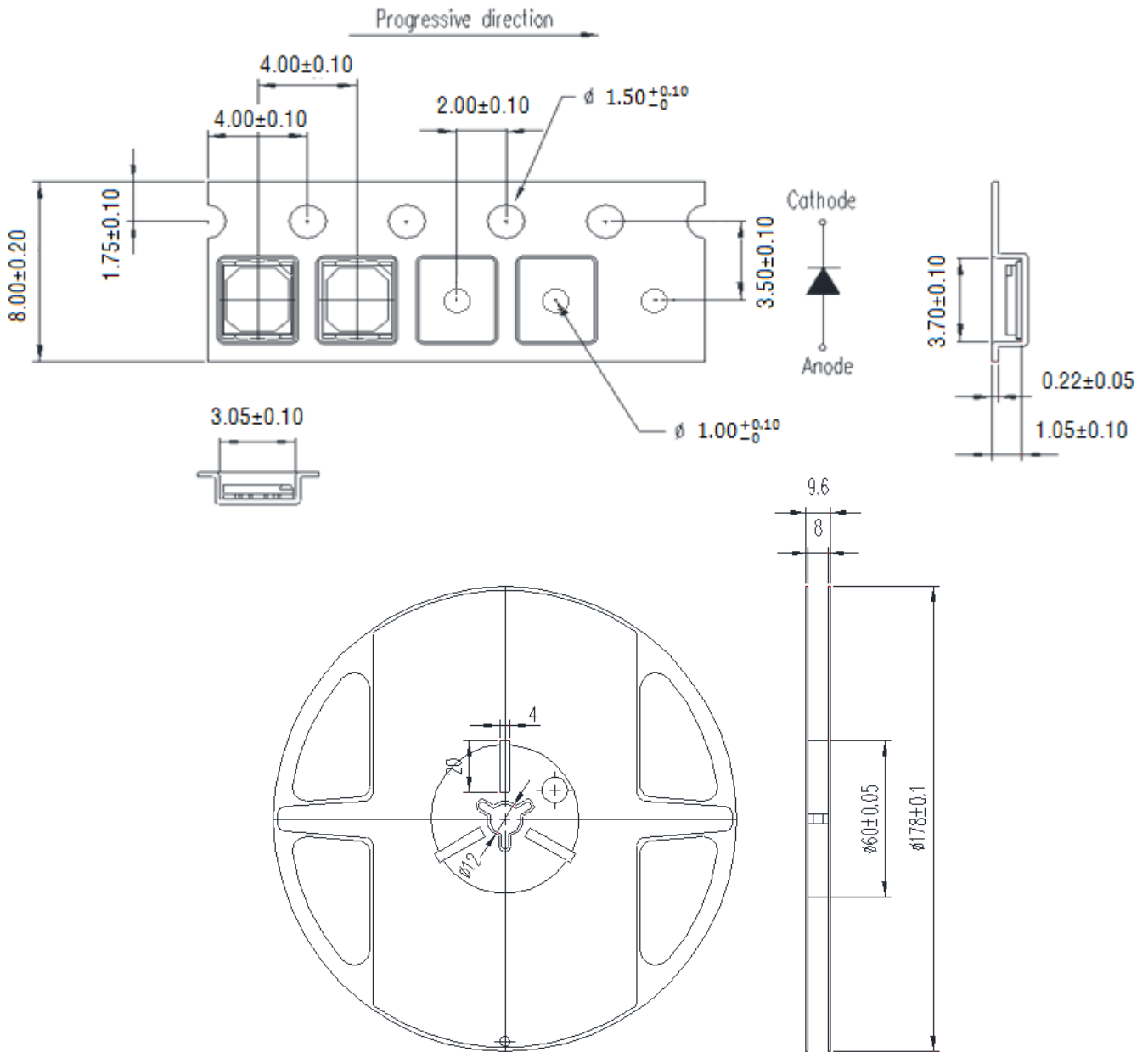
Gradual Cooling (Avoid quenching).

Lead solder		Lead-free solder	
Pre-heat	120-150°C	Pre-heat	150-200°C
Pre-heat time	120 sec.Max.	Pre-heat time	120 sec.Max.
Peak Temperature	240°C Max.	Peak Temperature	260°C Max.
Soldering time condition	10 sec.Max.	Soldering time condition	10 sec.Max.

Lead Solder	Lead-free Solder
	

Notes:

The encapsulated material of the LEDs is silicone . Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the picking up nozzle, the pressure on the silicone resin should be proper.

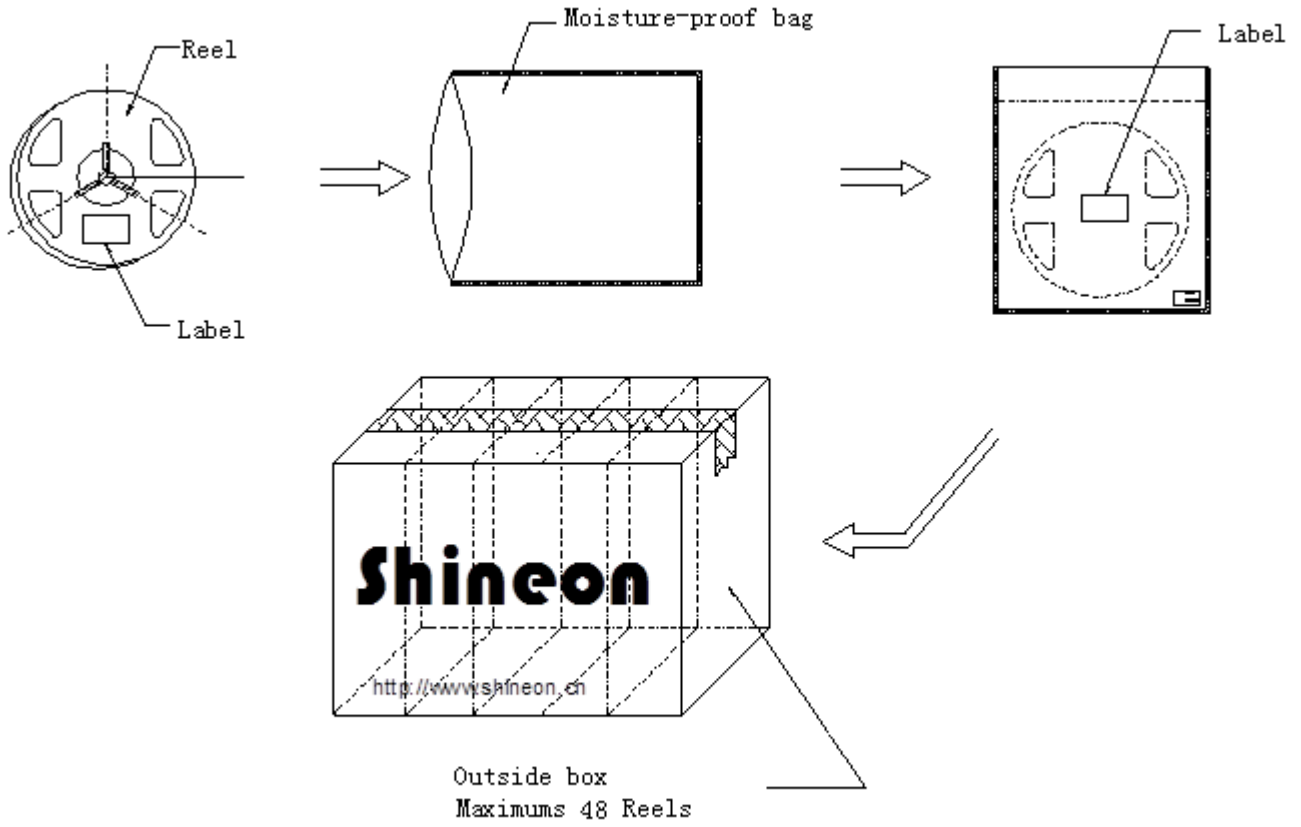
TAPE AND REEL


Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit=mm

Notes:

- (1) Quantity : 3,500pcs/Reel
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be $\pm 0.2\text{mm}$
- (3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10 °to the carrier tape
- (4) Package : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package.

PACKAGING



PRECAUTION FOR USE

- (1) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When washing is required, IPA should be used.
- (2) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.
- (3) LEDs must be stored to maintain a clean atmosphere. If the LEDs are stored for 3 months or more after being shipped from ShineOn, a sealed container with a nitrogen atmosphere should be used for storage.
- (4) The LEDs must be used within four weeks after opening the moisture proof packing. Repack unused Products with anti-moisture packing, fold to close any opening and then store in a dry place.
- (5) The appearance and specifications of the product may be modified for improvement without notice.
- (6) This LED is sensitive to the static electricity and surge. It is recommended to use a wrist Band or anti-electrostatic glove when handling the LEDs.
- (7) On manual soldering, a solder tip must be needed as grounded for usage. If over voltage which exceeds the absolute maximum rating is applied to LEDs, it will cause damage LEDs and result in destruction. Damaged LEDs will show some unusual characteristics such as leak current remarkably increase ,turn-on voltage becomes lower and the LEDs get unlighted at low current.